



US00D651990S

(12) **United States Design Patent**
Shimada et al.

(10) **Patent No.:** **US D651,990 S**
(45) **Date of Patent:** **** Jan. 10, 2012**

(54) **SEMICONDUCTOR MANUFACTURING EQUIPMENT**

(75) Inventors: **Masakazu Shimada**, Toyama (JP);
Takashi Nogami, Toyama (JP); **Satoshi Aizawa**, Toyama (JP); **Seiyo Nakashima**, Toyama (JP); **Tomoyuki Yamada**, Toyama (JP); **Shinobu Sugiura**, Toyama (JP); **Yukinori Aburatani**, Toyama (JP); **Mitsuhiro Nagata**, Kodaira (JP)

(73) Assignee: **Hitachi Kokusai Electric Inc.**, Tokyo (JP)

(**) Term: **14 Years**

(21) Appl. No.: **29/371,214**

(22) Filed: **Nov. 29, 2010**

(30) **Foreign Application Priority Data**

Jun. 1, 2010 (JP) 2010-013455

(51) **LOC (9) Cl.** **13-03**

(52) **U.S. Cl.** **D13/182**

(58) **Field of Classification Search** D13/182,
D13/184; 118/500, 719; 250/307, 310, 311;
414/217, 935, 936, 937

See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

5,810,538	A *	9/1998	Ozawa et al.	414/217
6,547,660	B1 *	4/2003	Suenaga et al.	454/187
6,580,087	B1 *	6/2003	Suzuki et al.	250/559.4
6,945,746	B2 *	9/2005	Yamagishi et al.	414/217
7,039,499	B1 *	5/2006	Nasr et al.	700/245
7,607,879	B2 *	10/2009	Hall et al.	414/217
D607,424	S *	1/2010	Hosaka et al.	D13/182
2006/0120833	A1 *	6/2006	Bonora et al.	414/217
2007/0098527	A1 *	5/2007	Hall et al.	414/222.01
2008/0166208	A1 *	7/2008	Lester et al.	414/217
2008/0317581	A1 *	12/2008	Makino et al.	414/939
2011/0123300	A1 *	5/2011	Hashimoto	414/217
2011/0236159	A1 *	9/2011	Lenz	414/217

* cited by examiner

Primary Examiner — Selina Sikder

(74) *Attorney, Agent, or Firm* — Stites & Harbison PLLC; Juan Carlos A. Marquez, Esq.

(57) **CLAIM**

We claim the ornamental design for a semiconductor manufacturing equipment, as shown and described.

DESCRIPTION

FIG. 1 is a front, top and right side perspective view of an semiconductor manufacturing equipment showing our new design;

FIG. 2 is a front elevational view thereof;

FIG. 3 is a rear elevational view thereof;

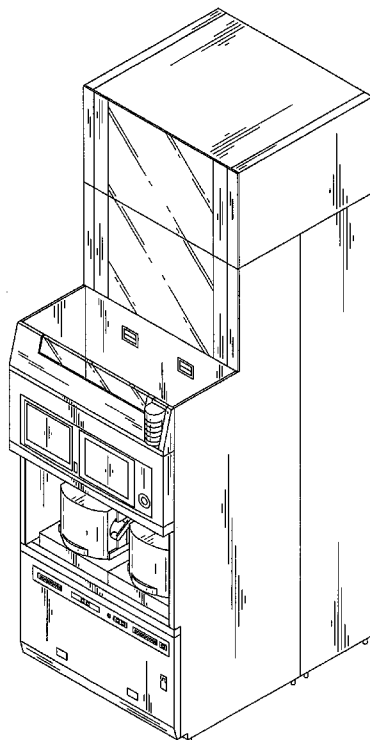
FIG. 4 is a top plan view thereof;

FIG. 5 is a bottom plan view thereof;

FIG. 6 is a left side elevational view thereof; and,

FIG. 7 is a right side elevational view thereof.

1 Claim, 5 Drawing Sheets



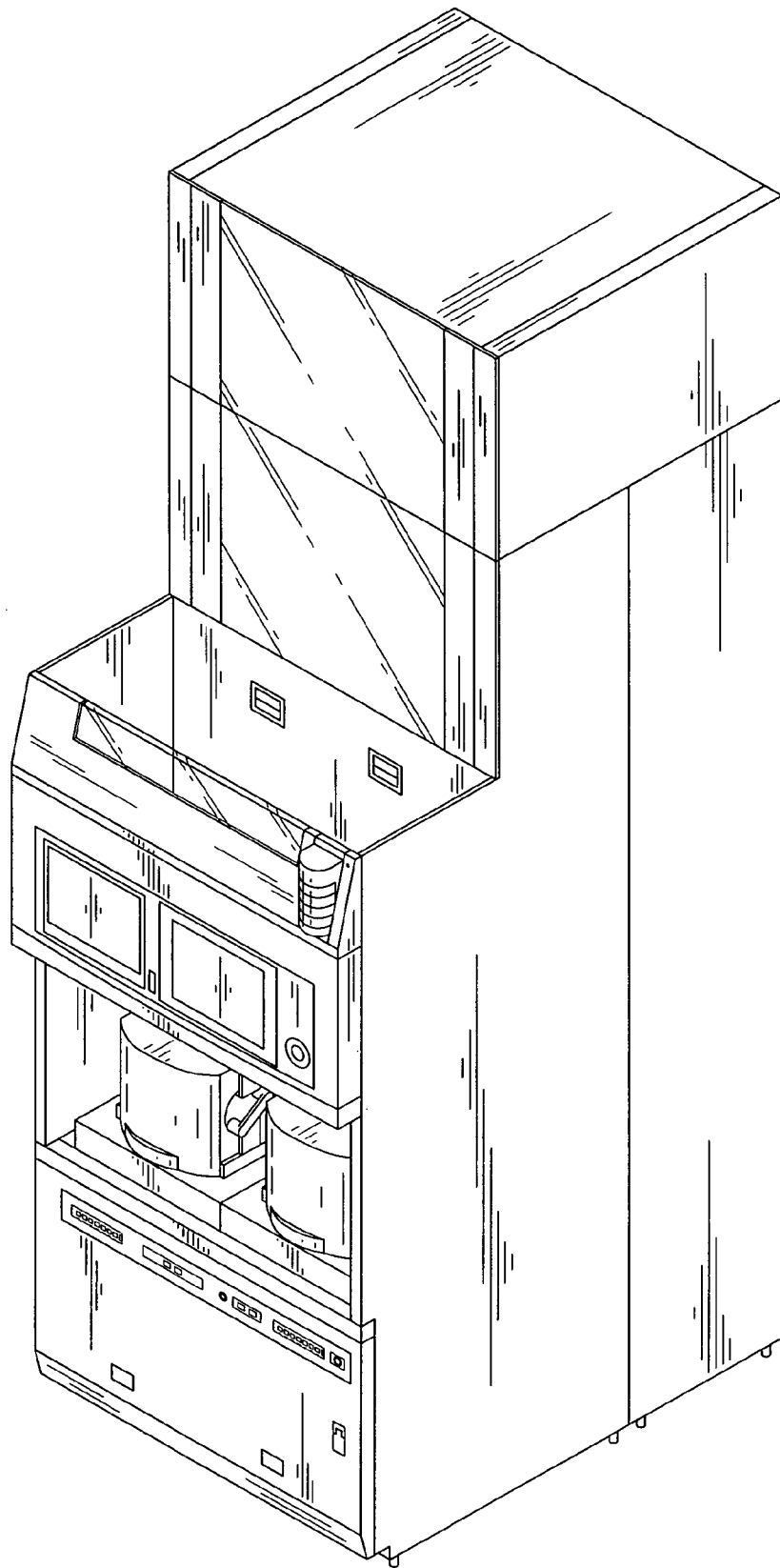


FIG. 1

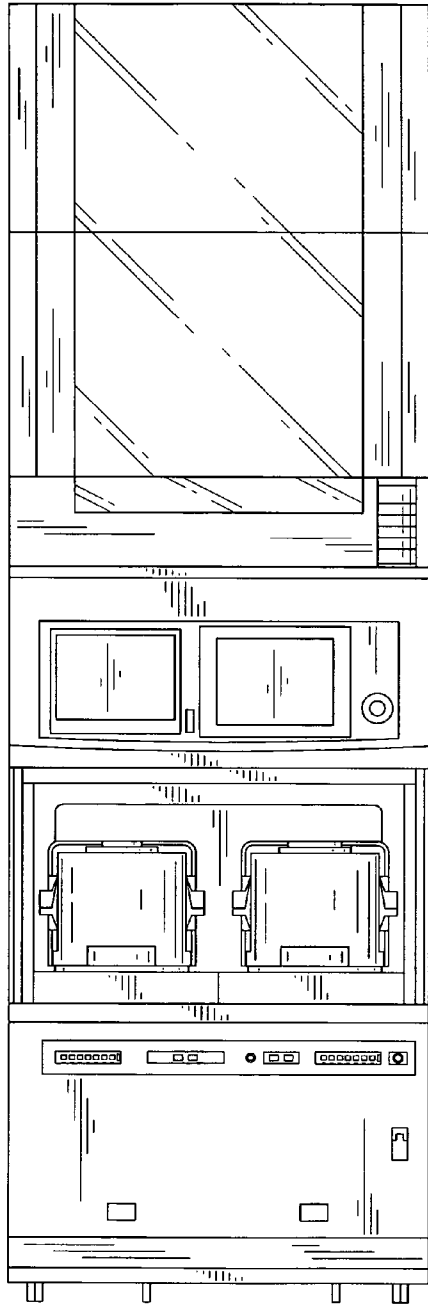


FIG. 2

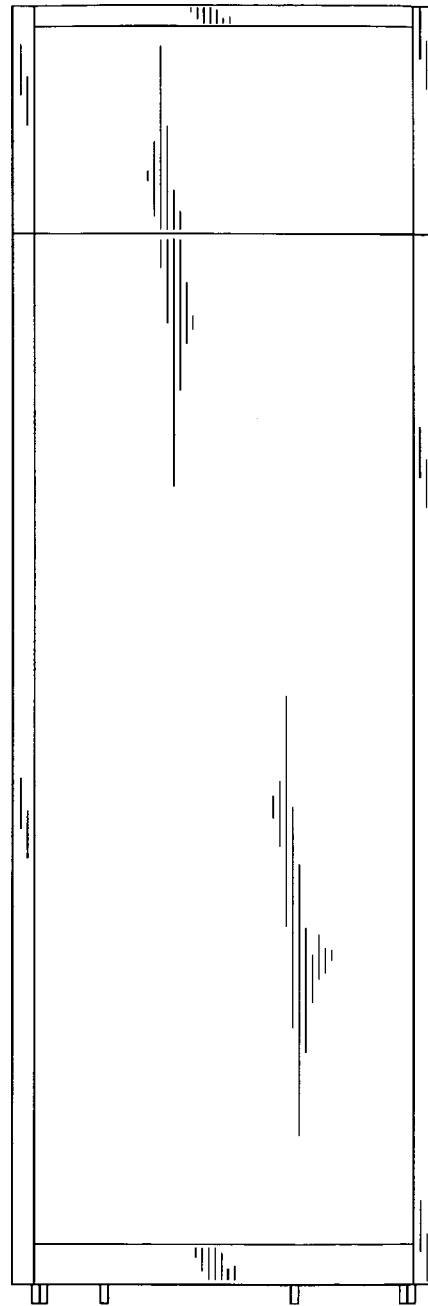


FIG. 3

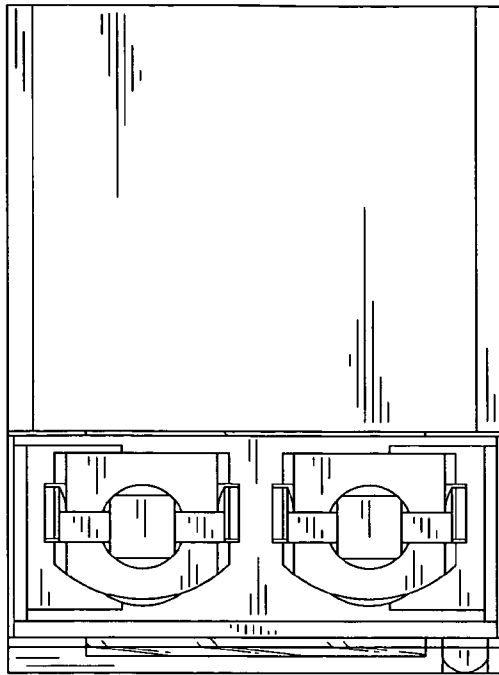


FIG. 4

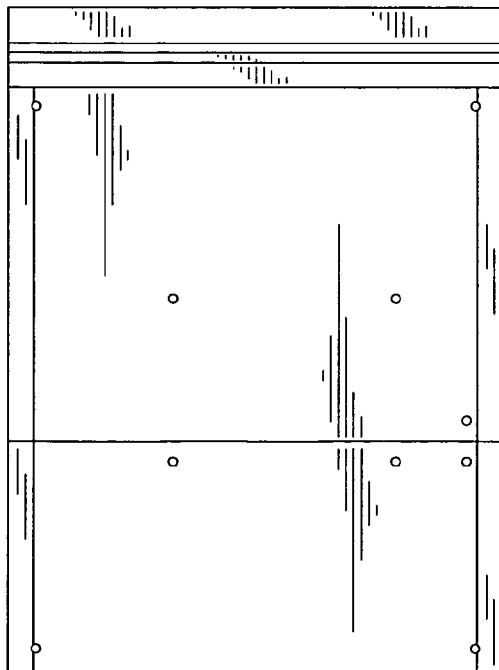


FIG. 5

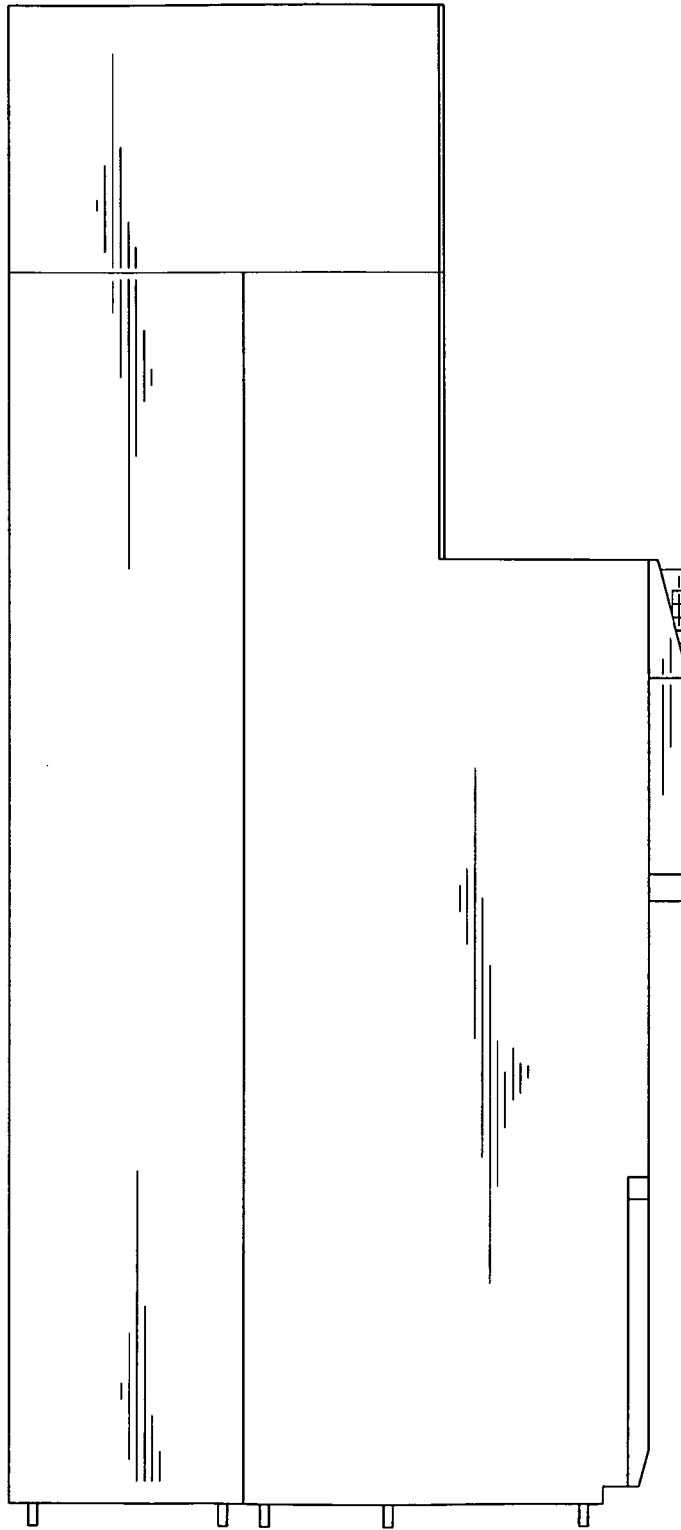


FIG. 6

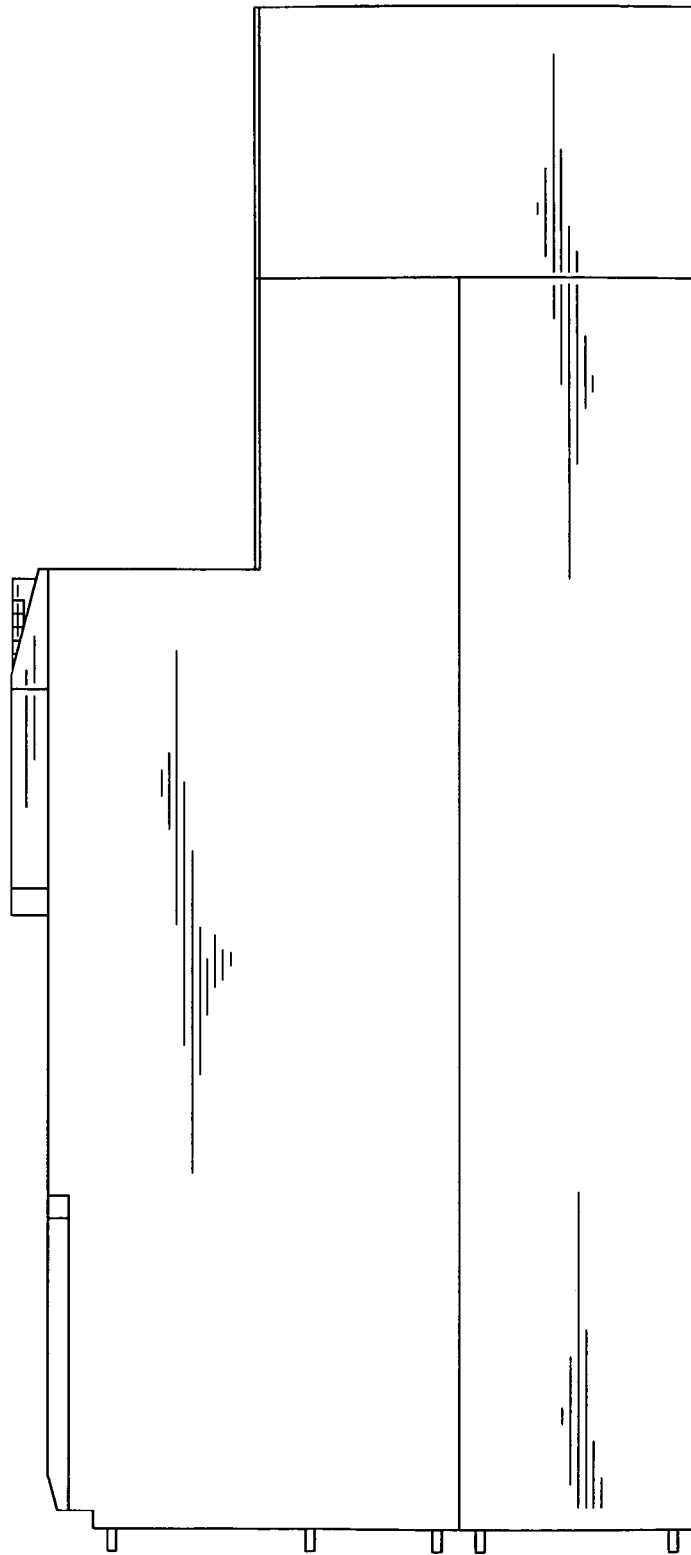


FIG. 7